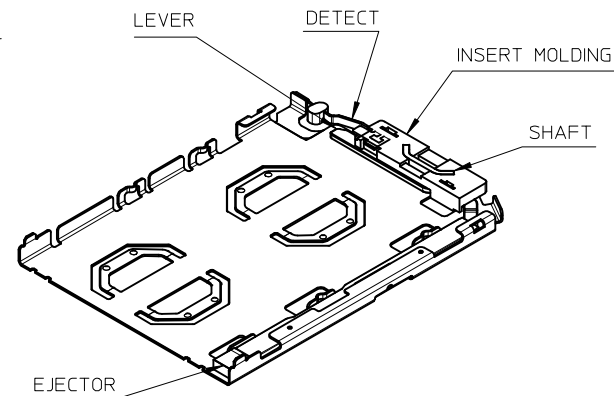
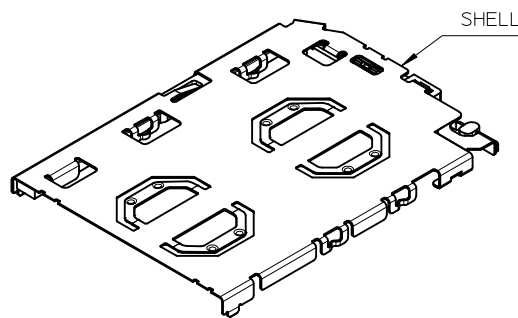


10 9 8 7 6 5 4 3 2 1

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.



NOTES:

1. MATERIALS:

INSERT MOLD HOUSING: LCP, UL94V-0;
LEVER, SHAFT, EJECTOR, SHELL: STAINLESS STEEL;
DETECT SPRING: COPPER ALLOY;

2. FINISHES:

DETECT SPRING:

1.27um MIN. NICKEL UNDERPLATING OVERALL;
0.127um MIN. GOLD PLATING ON CONTACT AREA;
1.27 um MIN. TIN PLATING ON SOLDERING TAIL;

SHELL:

1.27um MIN NICKEL UNDERPLATING OVERALL;
0.025um MIN GOLD PLATING ON CONTACT AREA AND SOLDERING AREA;
SHAFT: 1.27um MIN TIN ON SOLDERING TAIL;

3. PRODUCT SPECIFICATION: PS-151031-001;

4. PACKAGING SPECIFICATION: PK-151031-001;PK-151032-001

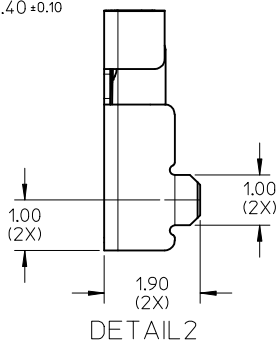
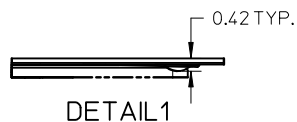
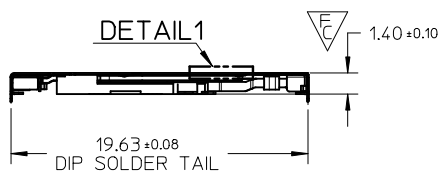
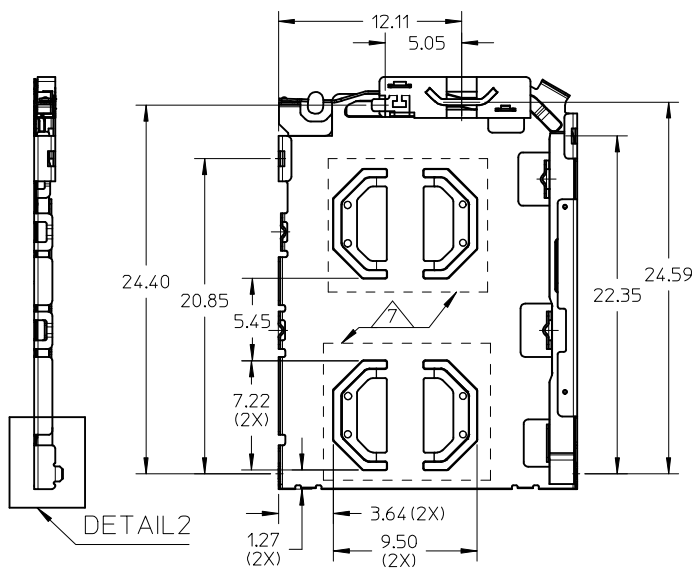
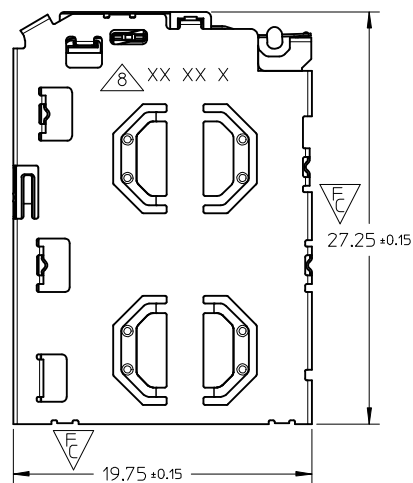
5. SOLDER TAIL COPLANARITY: 0.10 MM MAX BEFORE REFLOW

6. THIS PART IS A FRAME ONLY, IT SHOULD BE USED TOGETHER WITH 0.35MM BLOCK SIM 151032 FOR AN ENTIRE SIM POP OUT SYSTEM;

7. 0.10 MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF TRAY (WITH SIM CARD)

8. DATE CODE PRINTED: XX XX X

DAY
WEEK
YEAR



CHANGE BLOCK SIM AND TRAY
EC NO: S2014-0434
DRWN: JZENG
CHKD: JTAN02
APPR: KHLIM
2013/11/04
2014/01/02
2014/01/27

QUALITY SYMBOLS
F_A=0
F_G=4
F_P=0
DESCRIPTION
REV

GENERAL TOLERANCES (UNLESS SPECIFIED)
mm INCH
4 PLACES ± --- ± ---
3 PLACES ± --- ± ---
2 PLACES ± 0.20 ± ---
1 PLACE ± 0.20 ± ---
0 PLACE ± --- ± ---
ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY
DRAWN BY DATE
JZENG 2013/11/04
CHECKED BY DATE
JTAN02 2013/12/05
APPROVED BY DATE
KHLIM 2014/01/27
MATERIAL NO.
1510310001
SIZE
A3

SCALE
NTS
DESIGN UNITS
METRIC
THIRD ANGLE PROJECTION
TITLE
DUAL MICRO SIM FRAME
1.40 H
DOCUMENT NO.
SD-151031-0001
SHEET NO.
1 OF 5
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

E

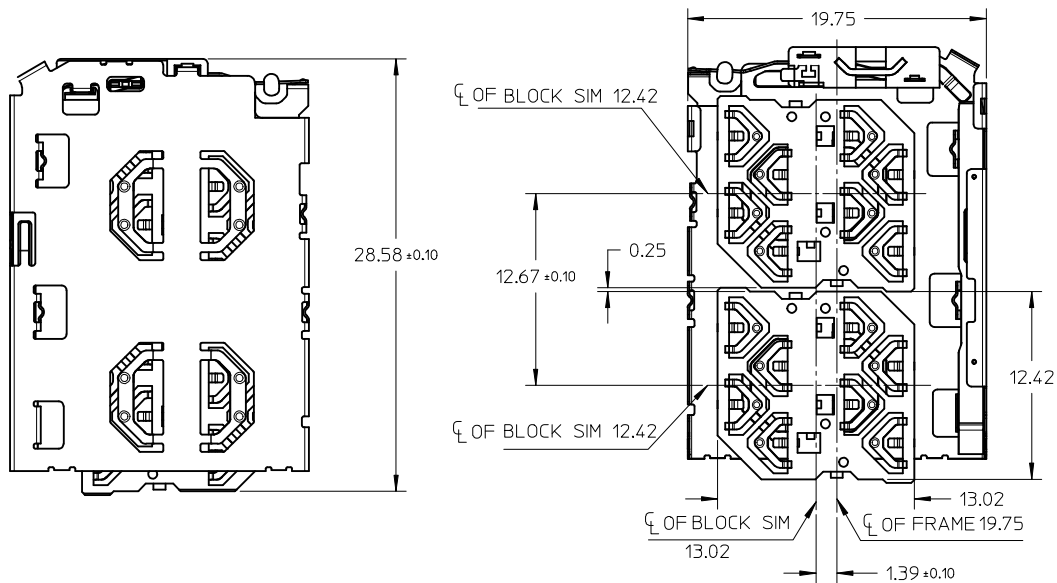
D

C

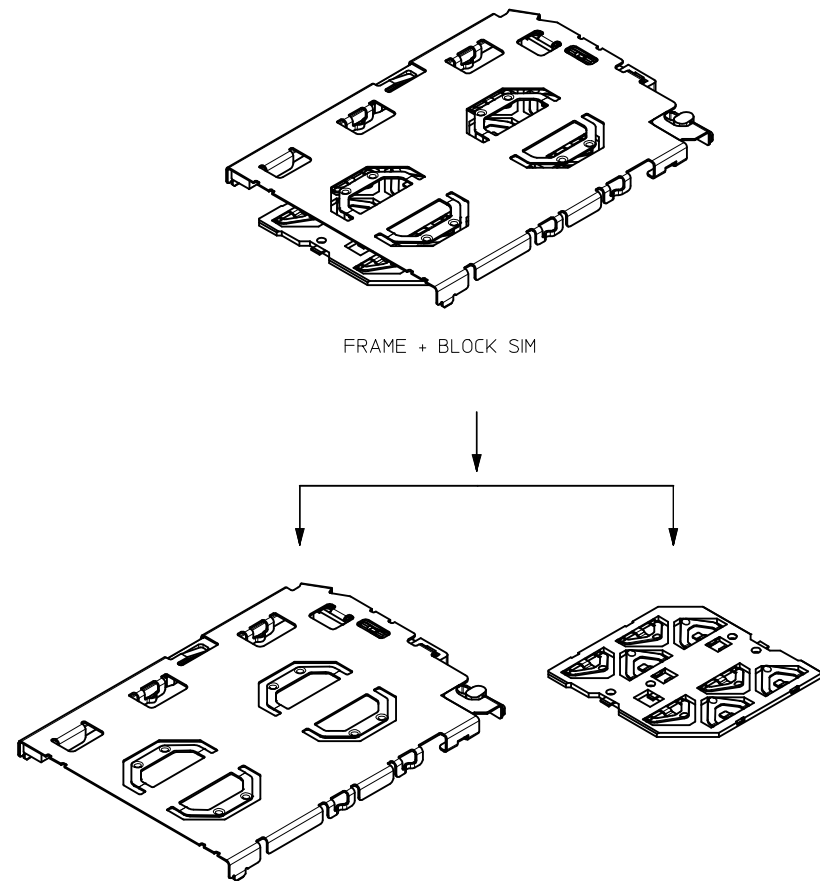
B

A

SIM CONNECTOR
(WITH 151032 BLOCK SIM CONNECTOR)



SIM CONNECTOR BOM



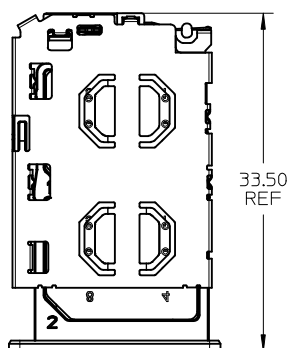
THIS DESIGN IS BASED ON DESIGN OBJECTIVES
AND IS STRICTLY TENTATIVE. IT MAY CHANGE
BASED ON RESULTS OF ADDITIONAL DESIGN
REVIEWS & VERIFICATIONS.

SEE SHEET1 EC NO: S2014-0434 DRWN: ZENG CHKD: TAN02 APPR: KHLIM	DESCRIPTION REV	QUALITY SYMBOLS F_A=0 F_B=0 F_C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION						
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE DUAL MICRO SIM FRAME 1.40 H							
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05								
			3 PLACES	± ---	± ---	APPROVED BY KHLIM		DATE 2014/01/27	molex						
			2 PLACES	± 0.20	± ---										
			1 PLACE	± 0.20	± ---	DOCUMENT NO. SD-151031-0001									
			0 PLACE	± ---	± ---										
			ANGULAR ± 3 °			MATERIAL NO. 1510310001		SHEET NO. 2 OF 5							
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

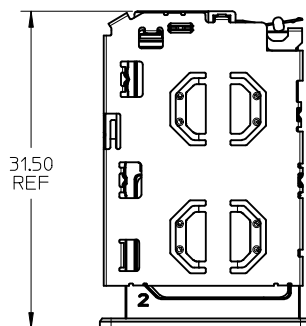
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

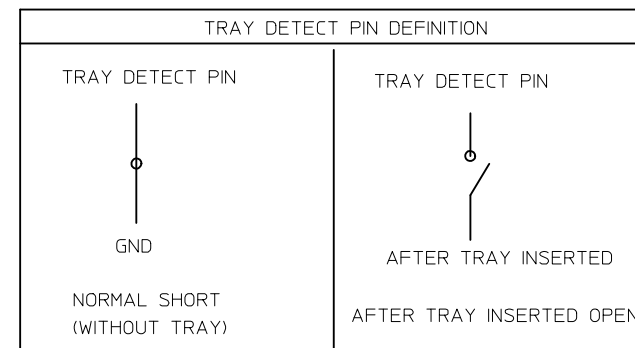
SIM CONNECTOR FRAME AND TRAY



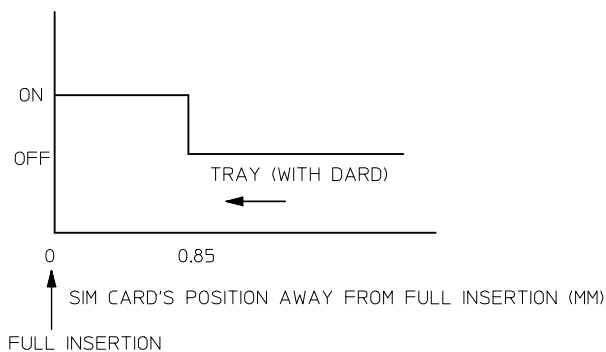
TRAY EJECTED POSITION



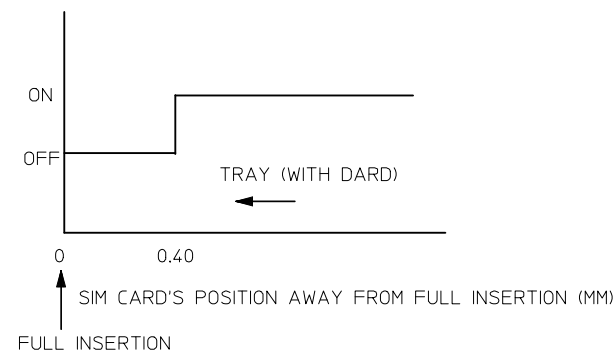
TRAY INSERTION POSITION



SIGNAL PIN

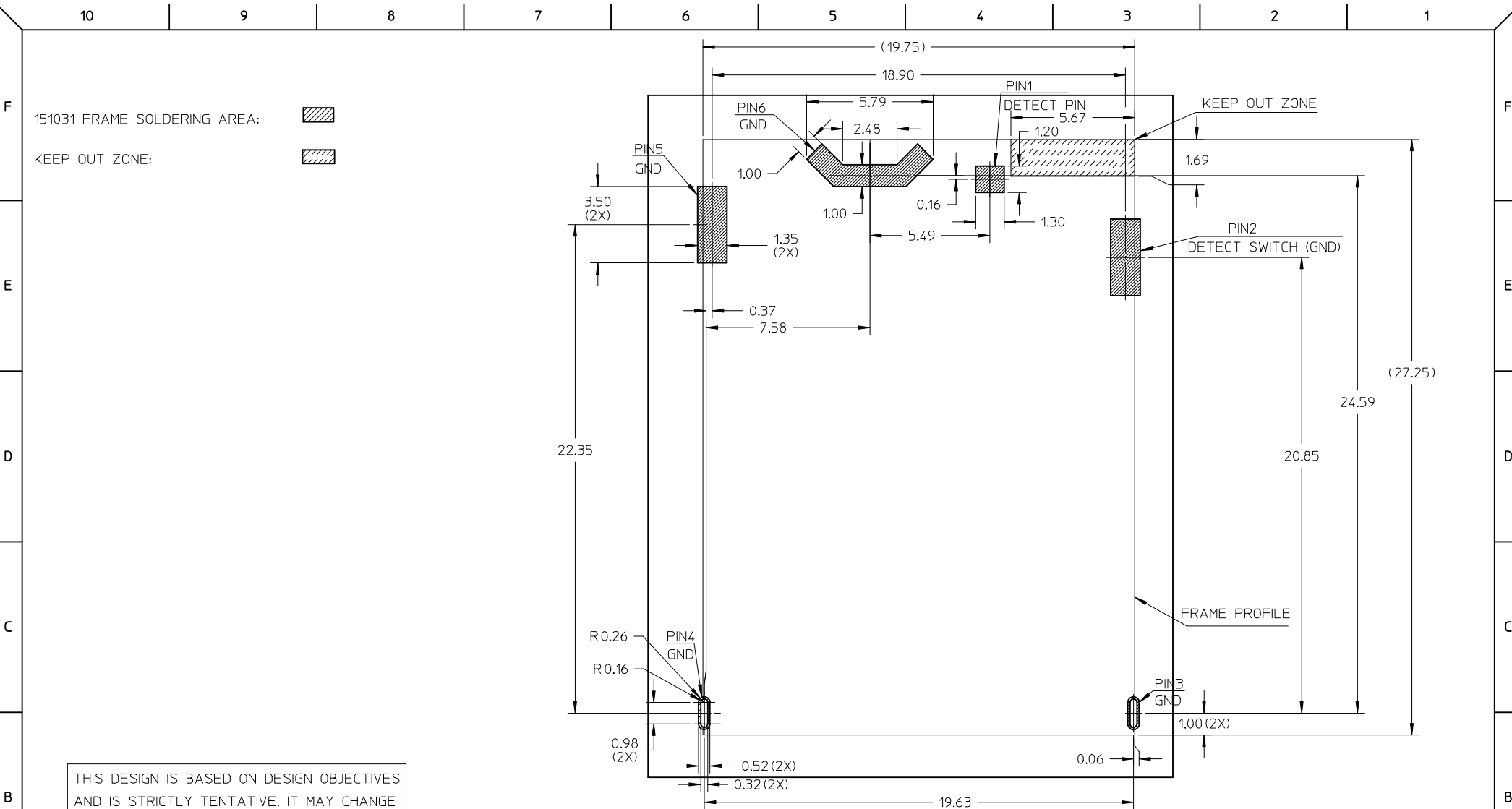


DETECT SWITCH PIN



ENTER DESCRIPTION EC NO: S2014-0434 DRWN: JZENG CHKD: JTAN02 APPR: KHLIM	DESCRIPTION REV 7	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE DUAL MICRO SIM FRAME 1.40 H				
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05					
			3 PLACES	± ---	± ---	APPROVED BY KHLIM	DATE 2014/01/27					
			2 PLACES	± 0.20	± ---	molex						
			1 PLACE	± 0.20	± ---							
0 PLACE	± ---	± ---	MATERIAL NO. 1510310001		DOCUMENT NO. SD-151031-0001			SHEET NO. 3 OF 5				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

9 8 7 6 5 4 3 2 1

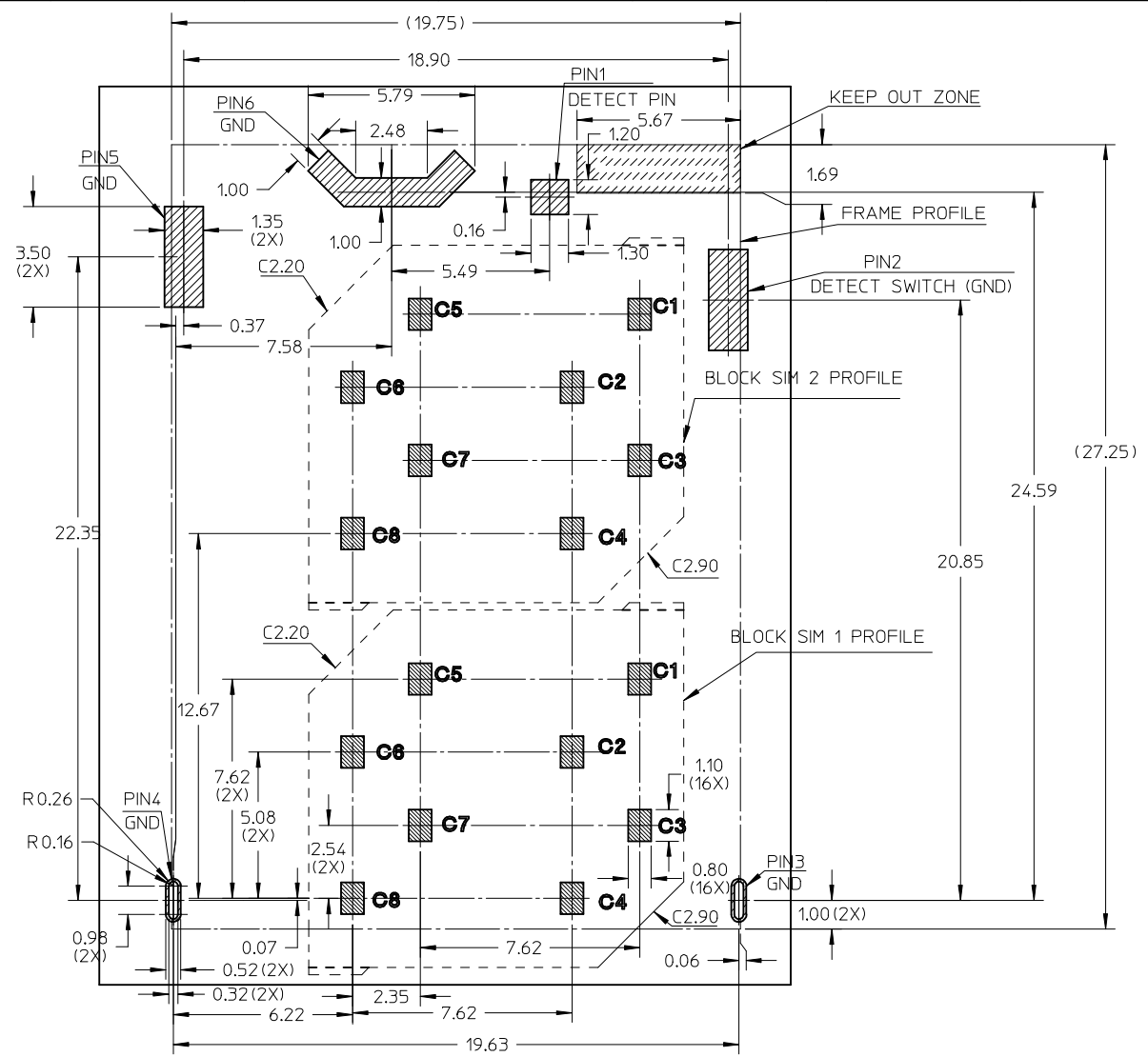


THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ± 0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JTAN02 APPR: KHLIM	DESCRIPTION REV	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION				
				mm	INCH	DRAWN BY JZENG	DATE 2013/11/04	TITLE DUAL MICRO SIM FRAME 1.40 H					
			4 PLACES	± ---	± ---	CHECKED BY JTAN02	DATE 2013/12/05						
			3 PLACES	± ---	± ---	APPROVED BY KHLIM		DATE 2014/01/27	molex				
			2 PLACES	± 0.20	± ---	MATERIAL NO. 1510310001		DOCUMENT NO. SD-151031-0001					
			1 PLACE	± 0.20	± ---	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							
0 PLACE	± ---	± ---											
ANGULAR ± 3 °													
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS													

151031 FRAME SOLDERING AREA: 
151032 BLOCK SIM SOLDERING AREA: 
KEEP OUT ZONE: 



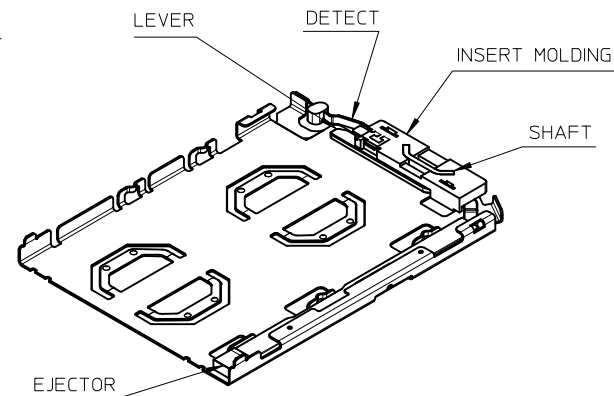
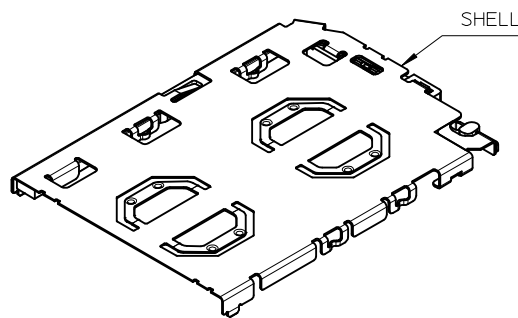
THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ±0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JTAN02 APPR: KHL IM 7	DESCRIPTION REV	QUALITY SYMBOLS <
--	--------------------	--

10 9 8 7 6 5 4 3 2 1

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.



NOTES:

1. MATERIALS:

INSERT MOLD HOUSING: LCP, UL94V-0;

LEVER, SHAFT, EJECTOR, SHELL: STAINLESS STEEL;

DETECT SPRING: COPPER ALLOY;

2. FINISHES:

DETECT SPRING:

1.27um MIN. NICKEL UNDERPLATING OVERALL;

0.127um MIN. GOLD PLATING ON CONTACT AREA;

1.27 um MIN. TIN PLATING ON SOLDERING TAIL;

SHELL:

1.27um MIN NICKEL UNDERPLATING OVERALL;

0.025um MIN GOLD PLATING ON CONTACT AREA AND SOLDERING AREA;

SHAFT: 1.27um MIN TIN ON SOLDERING TAIL;

3. PRODUCT SPECIFICATION: PS-151031-001;

4. PACKAGING SPECIFICATION: PK-151031-001;PK-151032-001

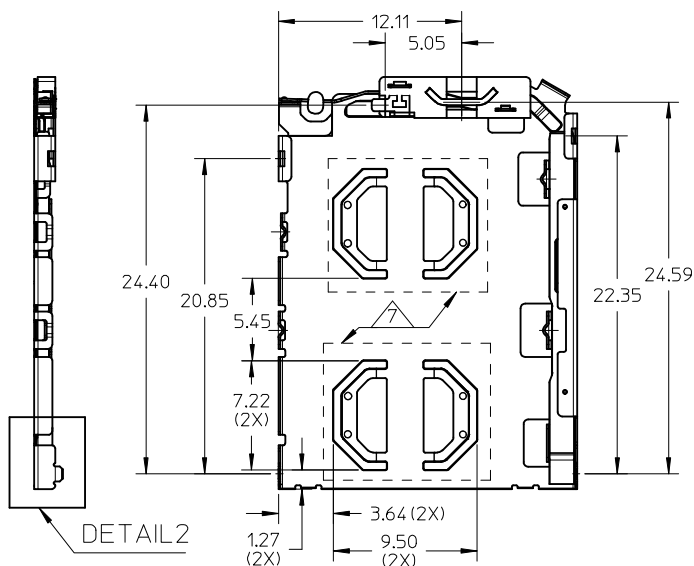
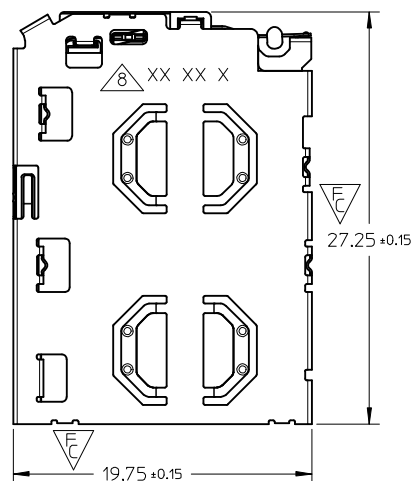
5. SOLDER TAIL COPLANARITY: 0.10 MM MAX BEFORE REFLOW

6. THIS PART IS A FRAME ONLY, IT SHOULD BE USED TOGETHER WITH 0.35MM BLOCK SIM 151032 FOR AN ENTIRE SIM POP OUT SYSTEM;

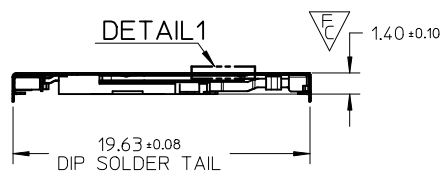
7. 0.10 MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF TRAY (WITH SIM CARD)

8. DATE CODE PRINTED: XX XX X

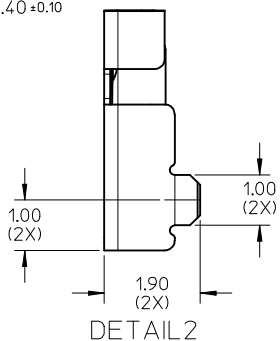
DAY
WEEK
YEAR



DETAIL2



DETAIL1



DETAIL2

UPDATED DRAWING
EC NO: S2014-0434
2013/12/13
DRWN: JZENG
CHKD: JIAN02
2014/01/02
APPR: KHLIM
2014/01/27

QUALITY SYMBOLS
F_A=0
F_G=4
F_P=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
JZENG	2013/12/13

CHECKED BY	DATE
KHLIM	2014/01/27

APPROVED BY	DATE
KHLIM	2014/01/27

MATERIAL NO.
1510310001

SCALE
NTS

DESIGN UNITS
METRIC

THIRD ANGLE PROJECTION

TITLE
DUAL MICRO SIM FRAME
1.40H

molex

DOCUMENT NO.
SD-151031-0002

SHEET NO.
1 OF 4

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F

E

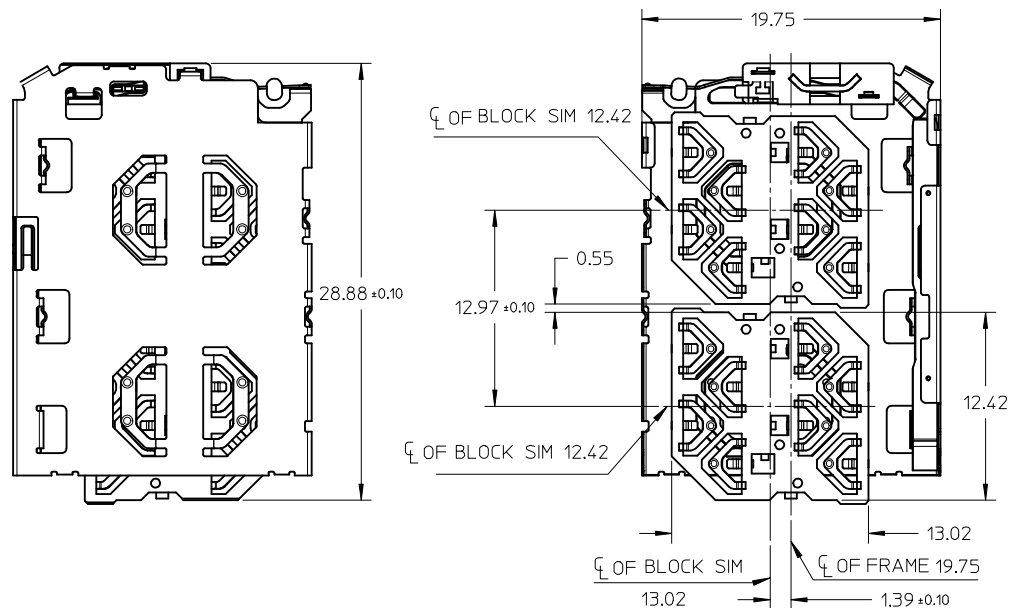
D

C

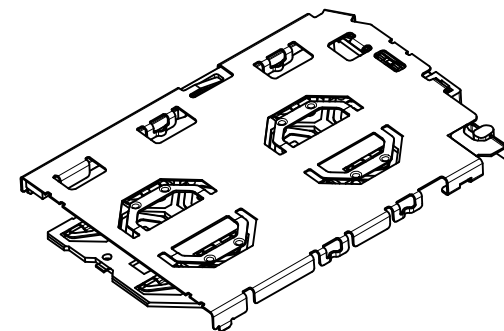
B

A

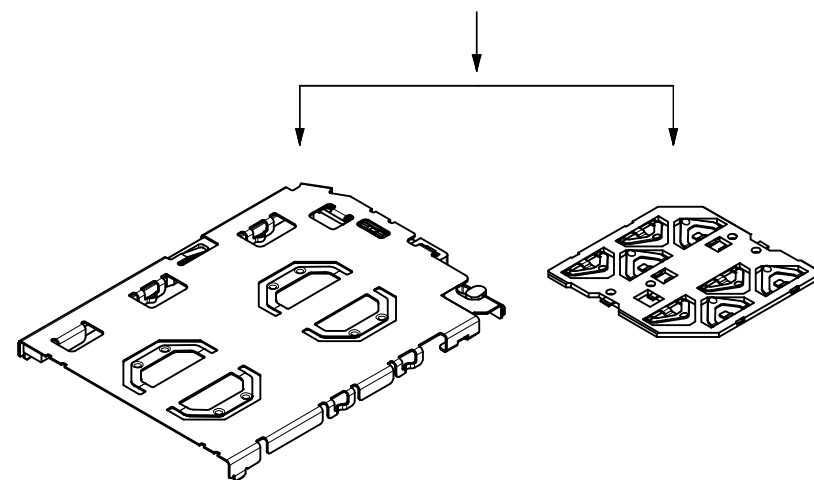
SIM CONNECTOR
(WITH 151032 BLOCK SIM CONNECTOR)



SIM CONNECTOR BOM



FRAME + BLOCK SIM



151032 SERIES

151031 SERIES

THIS DESIGN IS BASED ON DESIGN OBJECTIVES
AND IS STRICTLY TENTATIVE. IT MAY CHANGE
BASED ON RESULTS OF ADDITIONAL DESIGN
REVIEWS & VERIFICATIONS.

SEE SHEET1
EC NO: S2014-0434
2013/12/13
DRWN: JZENG
2014/01/02
CHKD: JIAN02
APPR: KHL IM
2014/01/27

QUALITY
SYMBOLS
F_A=0
F_G=0
F_P=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY	DATE
JZENG	2013/12/13

CHECKED BY	DATE

APPROVED BY	DATE
KHL IM	2014/01/27

MATERIAL NO.
1510310001

SIZE
A3

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	

TITLE
DUAL MICRO SIM FRAME
1.40H

molex

DOCUMENT NO.
SD-151031-0002

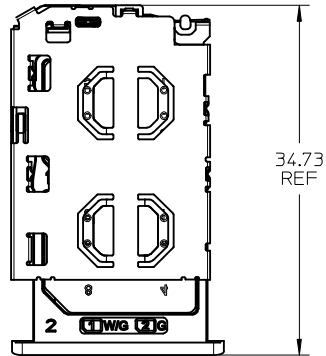
SHEET NO.
2 OF 4

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

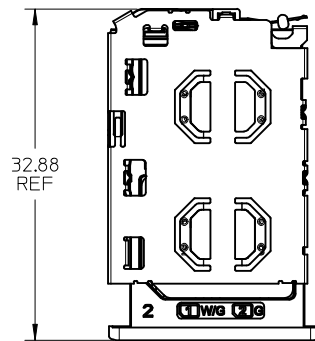
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

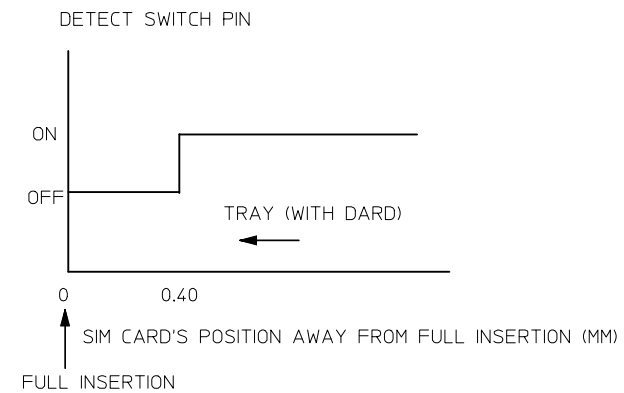
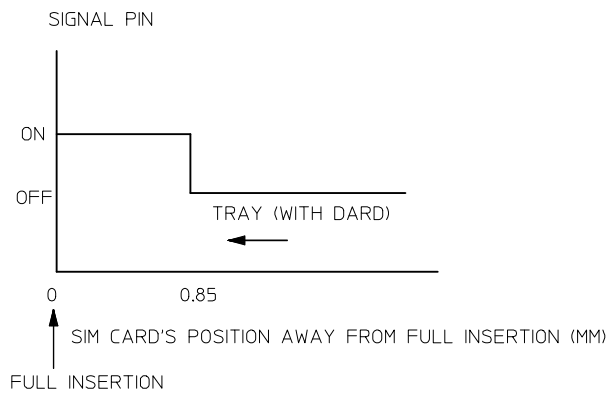
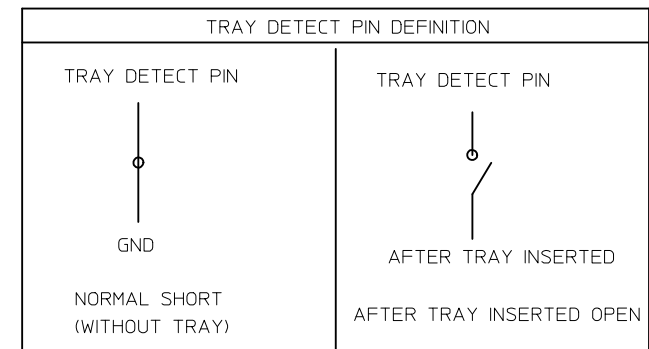
SIM CONNECTOR FRAME AND TRAY



TRAY EJECTED POSITION



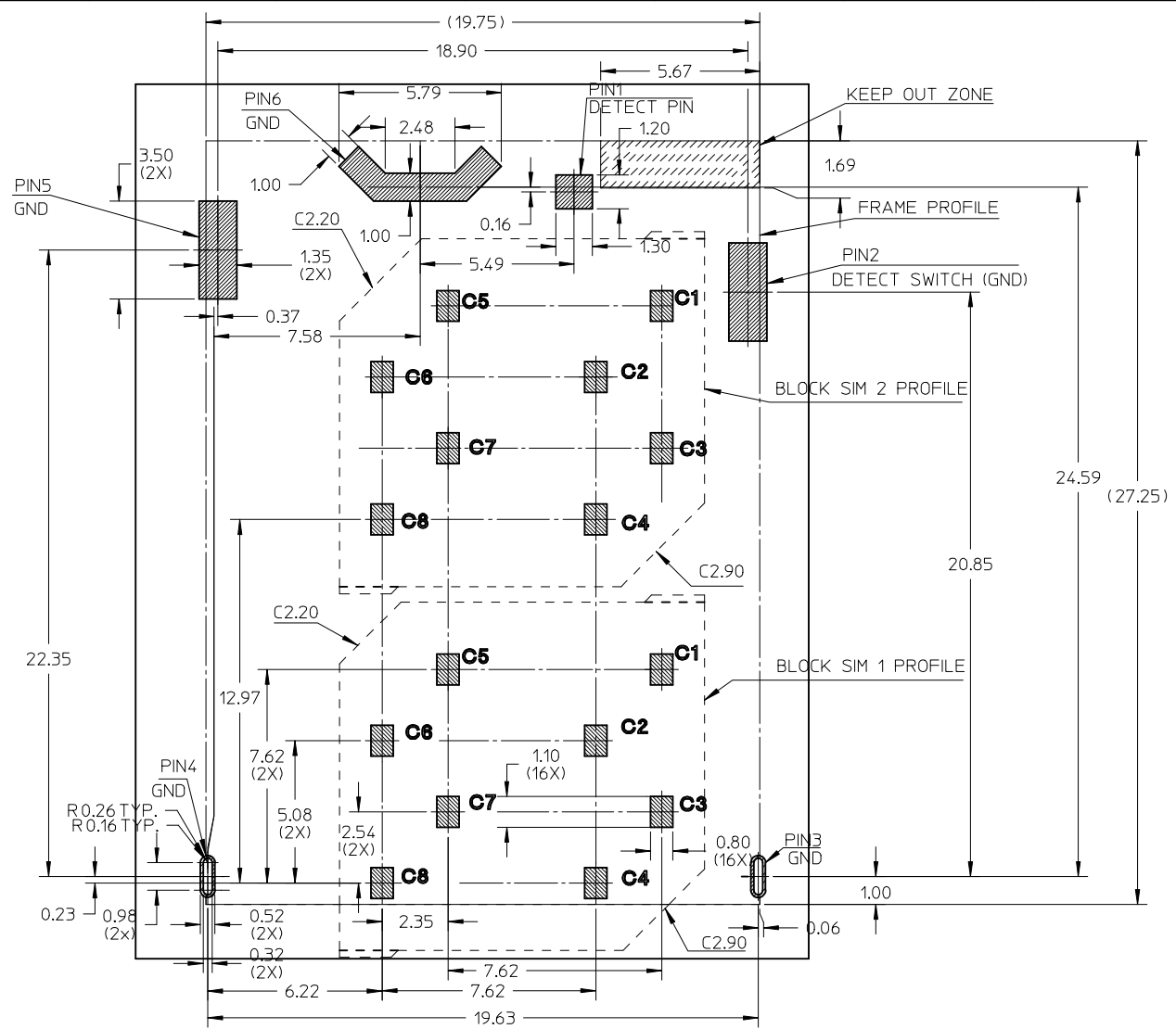
TRAY INSERTION POSITION



SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JIAN02 APPR: KHLIM	DESCRIPTION	QUALITY SYMBOLS F_A=0 F_C=0 F_P=0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION					
					mm	INCH	DRAWN BY JZENG	DATE 2013/12/13	TITLE DUAL MICRO SIM FRAME 1.40H							
							CHECKED BY	DATE								
					4 PLACES	± ---	± ---	APPROVED BY KHLIM DATE 2014/01/27								
					3 PLACES	± ---	± ---									
					2 PLACES	± 0.20	± ---									
					1 PLACE	± 0.20	± ---									
					0 PLACE	± ---	± ---	molex								
					ANGULAR ± 3 °							MATERIAL NO.		DOCUMENT NO.		SHEET NO.
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							1510310001		SD-151031-0002		3 OF 4
REV						SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

9 8 7 6 5 4 3 2 1

151031 FRAME SOLDERING AREA: 
151032 BLOCK SIM SOLDERING AREA: 
KEEP OUT ZONE: 



THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ± 0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1 EC NO: S2014-0434 DRWN: JZENG CHKD: JIAN02 APPR: KHL IM	DESCRIPTION	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
				mm	INCH	DRAWN BY JZENG	DATE 2013/12/13	TITLE DUAL MICRO SIM FRAME 1.40H				
						CHECKED BY	DATE					
						APPROVED BY KHL IM	DATE 2014/01/27	molex				
						MATERIAL NO. 1510310001	DOCUMENT NO. SD-151031-0002					
				ANGULAR ± 3 °								
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
REV												

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru

www.lifeelectronics.ru